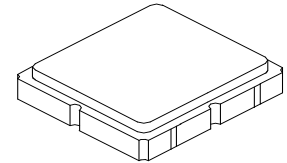


**SF2307D**

**353.5 MHz  
SAW Filter**



**SM3838-6**

- **Low-loss SAW Filter**
- **3.8 x 3.8 x 1.4 mm Surface-mount Package**
- **Complies with Directive 2002/95/EC (RoHS)**
- **Moisture Sensitivity Level: 1**

**Absolute Maximum Ratings**

Rating	Value	Units
Maximum Incident Power in Passband	15	dBm
Maximum DC Voltage on any Non-ground Terminal	3	VDC
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Operating Temperature Range	-30 to +80	°C
Suitable for Lead-free Soldering - Maximum Soldering Profile	260 °C for 30 s	

**Electrical Characteristics**

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	$f_C$			353.5		MHz
Insertion Loss	IL			1.5	3.5	dB
Bandwidth	BW			7		MHz
Amplitude Ripple, $f_C \pm 3.5$ MHz					3.0	dB <sub>P-P</sub>
Rejection Referenced to IL:						dB
0.3 to 345.0 MHz			30	50		
360 to 362 MHz			6	23		
362 to 367 MHz			20	30		
367 to 2000 MHz			25	45		
VSWR, $f_C \pm 3.5$ MHz				1.5:1	2.0:1	

Case Style	SM3838-6 3.8 x 3.8 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	A57, <u>YWWS</u>					
Standard Reel Quantity	Reel Size 7 Inch					500 Pieces/Reel
	Reel Size 13 Inch					3000 Pieces/Reel

**Electrical Connections**

Connection	Terminals
Input Port	2
Output Port	5
Ground	All others

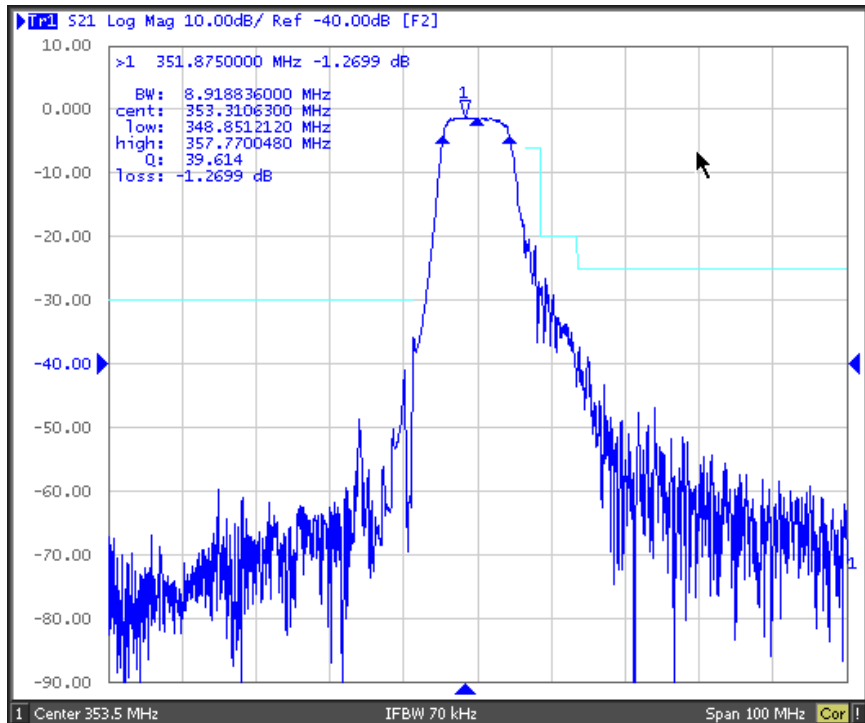
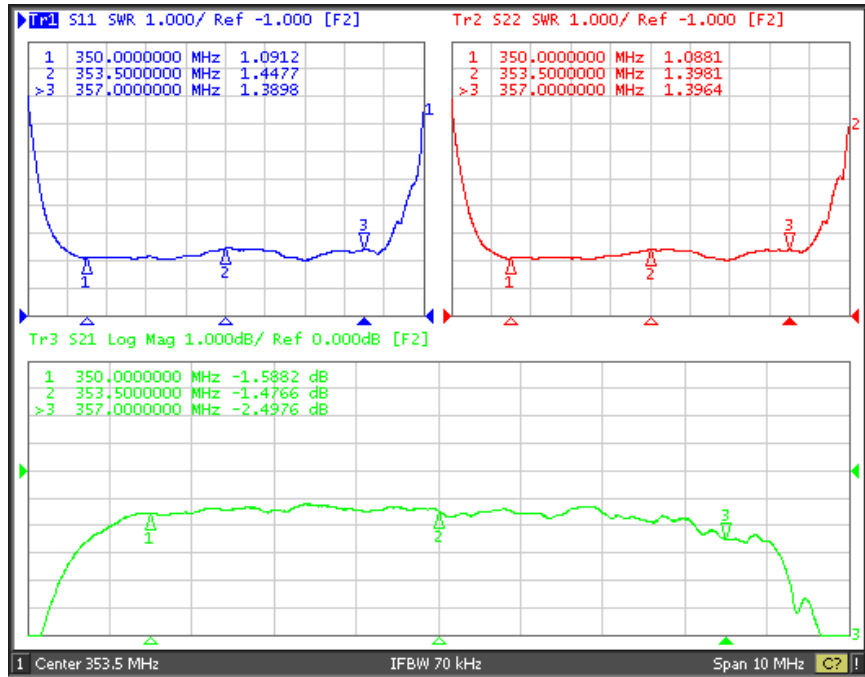


**CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

**NOTES:**

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

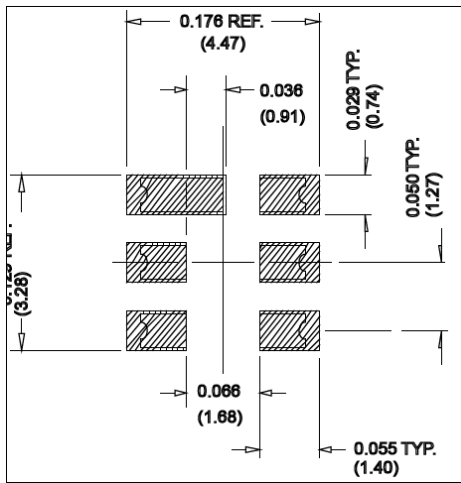
# Filter Response Plots



# SM3838-6 Case

## 6-Terminal Ceramic Surface-Mount Case

### 3.8 X 3.8 mm Nominal Footprint



PCB Footprint

#### Case Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	3.60	3.80	4.0	0.14	0.15	0.16
B	3.60	3.80	4.0	0.14	0.15	0.16
C	1.07	1.25	1.43	0.05	0.06	0.067
D	0.95	1.10	1.25	0.037	0.043	0.05
E	2.39	2.54	2.69	0.090	0.10	0.110
G	0.90	1.0	1.10	0.035	0.04	0.043
H	1.90	2.0	2.10	0.75	0.08	0.83
I	0.50	0.6	0.70	0.020	0.024	0.028
J	1.70	1.8	1.90	0.067	0.07	0.075

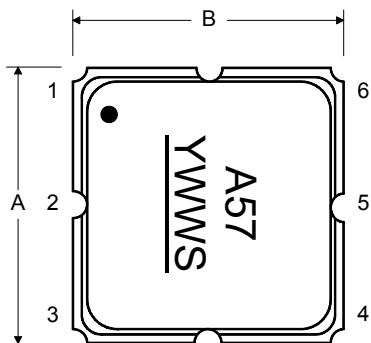
#### Electrical Connections

Connection		Terminals
Port 1	Single-ended Input	2
Port 2	Single-ended Output	5
	Ground	All others
Single-ended Operation Only		
Dot indicates Pin 1		

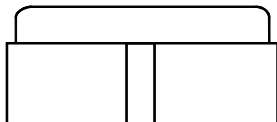
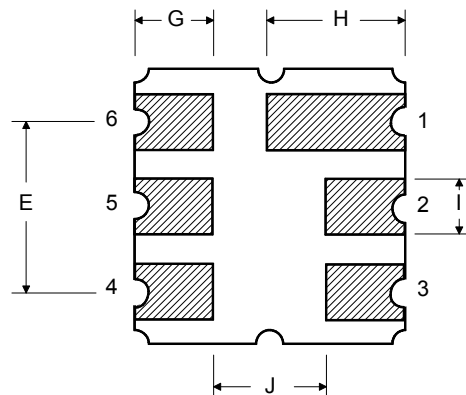
#### Materials

Solder Pad Plating	0.3 to 1.0 $\mu\text{m}$ Gold over 1.27 to 8.89 $\mu\text{m}$ Nickel
Lid Plating	2.0 to 3.0 $\mu\text{m}$ Nickel
Body	$\text{Al}_2\text{O}_3$ Ceramic

#### TOP VIEW

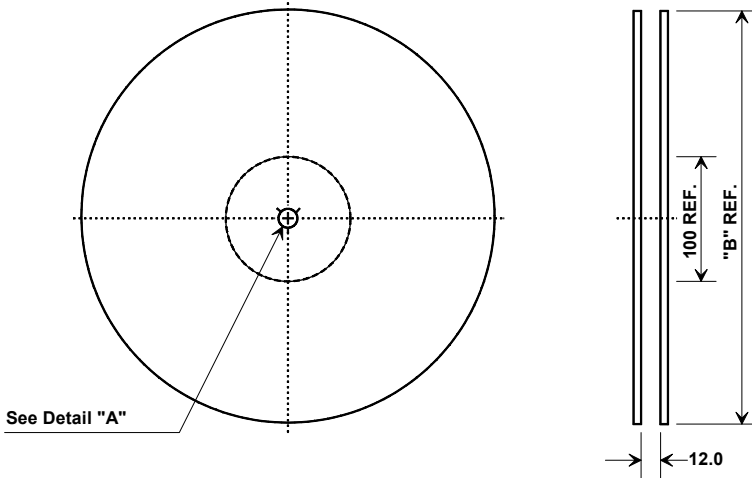


#### BOTTOM VIEW

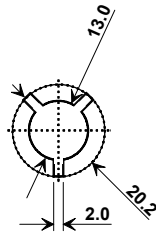


## Tape and Reel Specifications

Tape and Reel Standard per ANSI/EIA-481

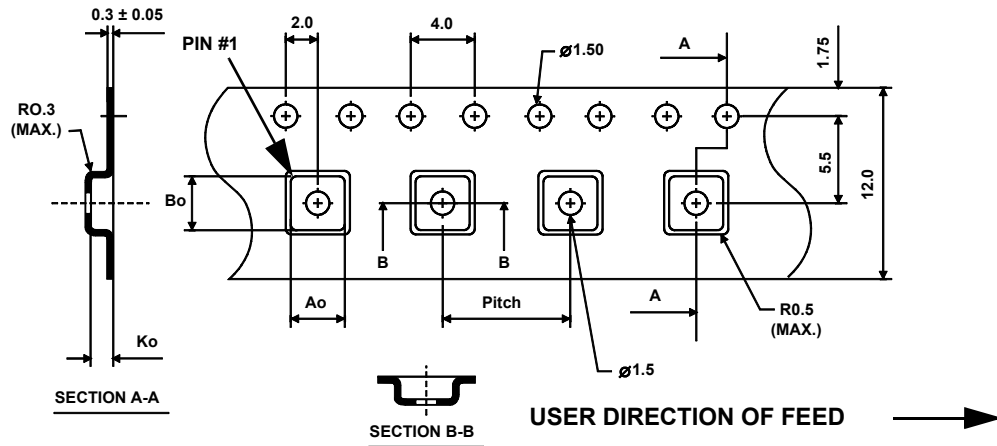


"B"		Quantity Per Reel
Nominal Size		
Inches	millimeters	
7	178	500
13	330	3000



### COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	4.25 mm
Bo	4.25 mm
Ko	1.30 mm
Pitch	8.0 mm
W	12.0 mm



## Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

